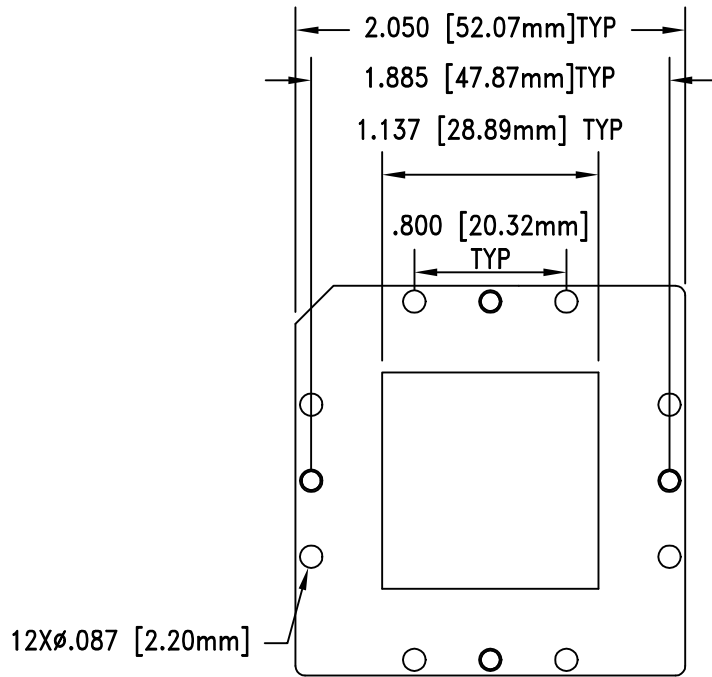


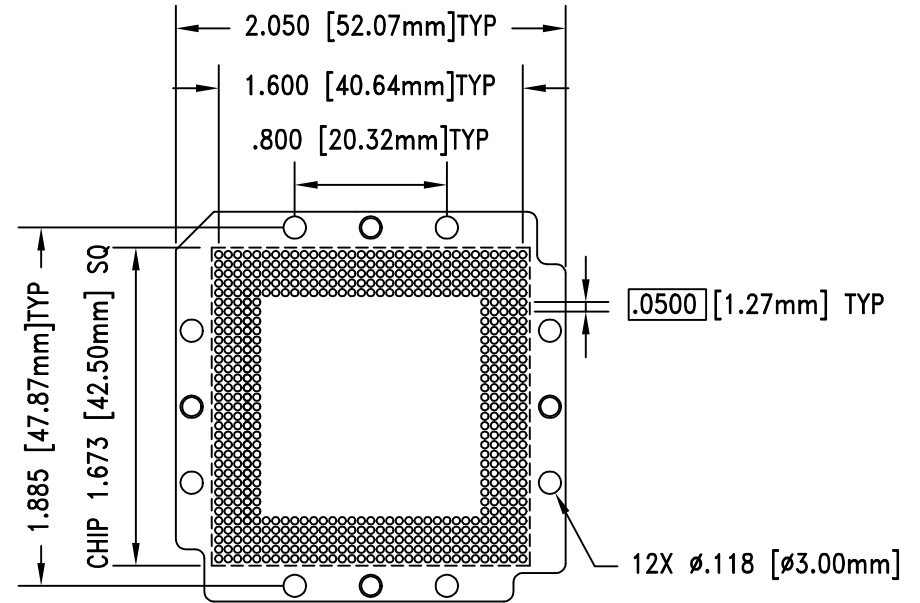
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	4/28/00	M.D.
B	UPDATED PAD LAYOUT AND DIMS	03/30/01	H.N.
C	ADDED CHIP SIZE	03/25/02	H.N.

SKT781

DOD 4781

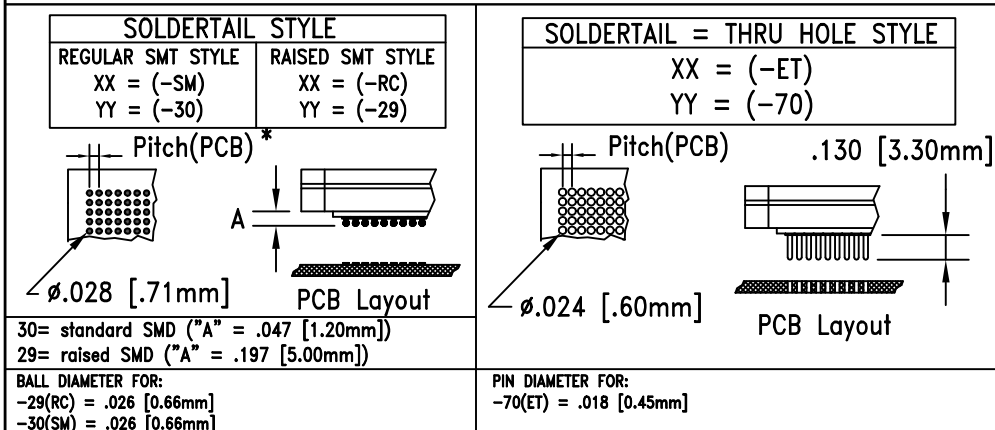


RETENTION FRAME



SOCKET

RECOMMENDED PAD LAYOUT



* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 560
LEAD PITCH	= 1.27mm
GRID SIZE	= 33X33
PACKAGE SIZE	= 42.50mm SQ

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

	Emulation Technology, Inc. — VLSI and SMT ADAPTERS and ACCESSORIES —	
	2344 Walsh Avenue, Bldg. F Santa Clara, Ca 95051	TEL:(408)982-0660 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 03/25/02	REVISION: C	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-BGA-33-560-XX	
DO NOT SCALE DRAWING			DESCRIPTION: BPW-560-2BG033-YY